

# PATENT ABSTRACTS OF JAPAN

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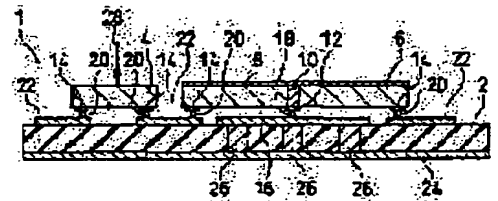
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## (54) SEMICONDUCTOR DEVICE

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To shut off noise entering a semiconductor device from the front and back sides by providing connection members for electrically connecting a semiconductor chip mount which mounts a semiconductor chip with element-forming faces opposed and has a conductive shield layer at a part facing the chip to this layer.

**SOLUTION:** A semiconductor chip 6 has electronic circuits on element-forming faces which are held a chip back face conductive layer 8 formed on the back of the chip 6 and conductive shield layer 16 formed, facing the chip 6, on a mounting face of an insulative board 2 and electrically connected to both the conductive layers 8, 16. The layer 8 mainly shuts off noise entering from the top face of the board 2 while the shield layer 16 mainly blocks noise entering from the bottom face, thus shutting off noise entering from the front and back sides of the semiconductor device.



## LEGAL STATUS

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